

ABSTRACT

The present invention provides a suction plate with which it is possible to form a half-cut groove with high accuracy. Provided is a suction plate for holding an object to be cut having a substrate and a resin layer, the suction plate including: a base member that includes a base part
5 which is disposed on a base that is provided with a suction mechanism, and a projection part which is formed so as to protrude upward from the base part and has a suction surface that is capable of sucking the resin layer; and a frame-like member that is disposed so as to surround the periphery of the projection part and has a mounting surface which is formed so as to be positioned above the suction surface, and on which the substrate can be mounted. At least one of the base member and
10 the frame-like member is provided with a discharge passage through which foreign substances in a specified space that is defined by the projection part and the frame-like member can be discharged to the outside of the specified space.

15 FIG. 13